

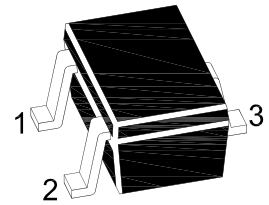
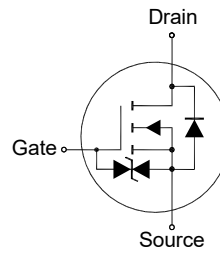
# MMFTN3008KE

## N-Channel Enhancement Mode MOSFET

### Features

- Surface-mounted package
- Built-in G-S Protection Diode
- Typical ESD Protection HBM Class 1C

Classification	Voltage Range(V)
0A	< 125
0B	125 to < 250
1A	250 to < 500
1B	500 to < 1000
1C	1000 to < 2000
2	2000 to < 4000
3A	4000 to < 8000
3B	≥ 8000



1.Gate 2.Source 3.Drain  
SOT-523 Plastic Package

### Applications

- Portable appliances
- Battery management

### Absolute Maximum Ratings(at $T_a = 25^\circ\text{C}$ unless otherwise specified)

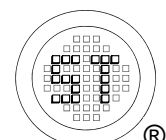
Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	V
Continuous Drain Current	$I_D$	350	mA
Pulsed Drain Current <sup>1)</sup>	$I_{DM}$	1.4	A
Total Power Dissipation <sup>2)</sup>	$P_{tot}$	200	mW
Operating Junction and Storage Temperature Range	$T_j, T_{stg}$	- 55 to + 150	$^\circ\text{C}$

### Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient <sup>2)</sup>	$R_{\theta JA}$	625	$^\circ\text{C/W}$

<sup>1)</sup> Pulse Test: Pulse Width  $\leq 100 \mu\text{s}$ , Duty Cycle  $\leq 2\%$ , Repetitive rating, pulse width limited by junction temperature  $T_{j(\text{MAX})}=150^\circ\text{C}$ .

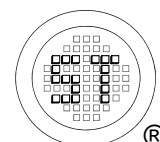
<sup>2)</sup> Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



# MMFTN3008KE

Characteristics at  $T_a = 25^\circ\text{C}$  unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit
<b>STATIC PARAMETERS</b>					
Drain-Source Breakdown Voltage at $I_D = 250 \mu\text{A}$	$V_{(BR)DSS}$	30	-	-	V
Zero Gate Voltage Drain Current at $V_{DS} = 30 \text{ V}$	$I_{DSS}$	-	-	1	$\mu\text{A}$
Gate-Source Leakage at $V_{GS} = \pm 8 \text{ V}$	$I_{GSS}$	-	-	$\pm 1$	$\mu\text{A}$
Gate-Source Threshold Voltage at $V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	$V_{GS(th)}$	0.4	-	1	V
Drain-Source On-State Resistance at $V_{GS} = 4.5 \text{ V}, I_D = 350 \text{ mA}$ at $V_{GS} = 2.5 \text{ V}, I_D = 200 \text{ mA}$ at $V_{GS} = 1.8 \text{ V}, I_D = 10 \text{ mA}$	$R_{DS(on)}$	-	-	1.4 2.1 2.8	$\Omega$
<b>DYNAMIC PARAMETERS</b>					
Forward Transconductance at $V_{DS} = 4.5 \text{ V}, I_D = 350 \text{ mA}$	$g_{fs}$	-	1.1	-	S
Input Capacitance at $V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	$C_{iss}$	-	54	-	pF
Output Capacitance at $V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	$C_{oss}$	-	9.4	-	pF
Reverse Transfer Capacitance at $V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	$C_{rss}$	-	4.4	-	pF
Gate charge total at $V_{DS} = 15 \text{ V}, I_D = 0.5 \text{ A}, V_{GS} = 4.5 \text{ V}$ at $V_{DS} = 15 \text{ V}, I_D = 0.5 \text{ A}, V_{GS} = 2.5 \text{ V}$	$Q_g$	-	0.8 0.42	-	nC
Gate to Source Charge at $V_{DS} = 15 \text{ V}, I_D = 0.5 \text{ A}, V_{GS} = 4.5 \text{ V}$	$Q_{gs}$	-	0.2	-	nC
Gate to Drain Charge at $V_{DS} = 15 \text{ V}, I_D = 0.5 \text{ A}, V_{GS} = 4.5 \text{ V}$	$Q_{gd}$	-	0.08	-	nC
Turn-On Delay Time at $V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 0.5 \text{ A}, R_G = 4.7 \Omega$	$t_{d(on)}$	-	1.8	-	ns
Turn-On Rise Time at $V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 0.5 \text{ A}, R_G = 4.7 \Omega$	$t_r$	-	18	-	ns
Turn-Off Delay Time at $V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 0.5 \text{ A}, R_G = 4.7 \Omega$	$t_{d(off)}$	-	29	-	ns
Turn-Off Fall Time at $V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 0.5 \text{ A}, R_G = 4.7 \Omega$	$t_f$	-	22	-	ns
<b>Body-Diode PARAMETERS</b>					
Drain-Source Diode Forward Voltage at $I_S = 350 \text{ mA}$	$V_{SD}$	-	-	1.2	V
Body-Diode Continuous Current	$I_S$	-	-	350	mA



## Electrical characteristics curves

Fig. 1 Typical Output Characteristics

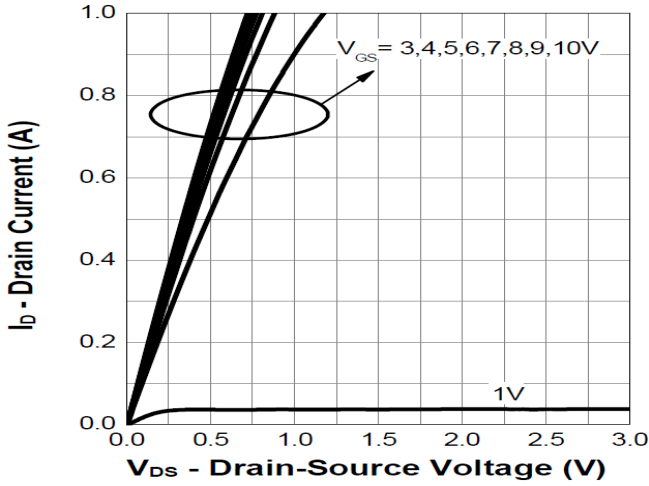


Fig. 2 Gate Threshold Variation vs.  $T_j$

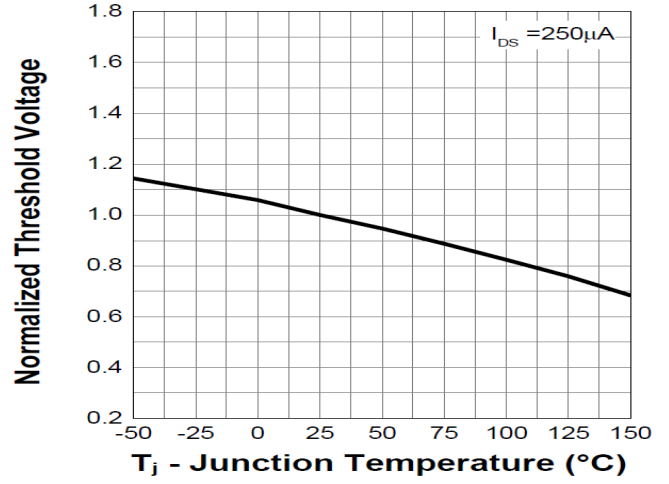


Fig. 3 on-Resistance vs. Drain Current

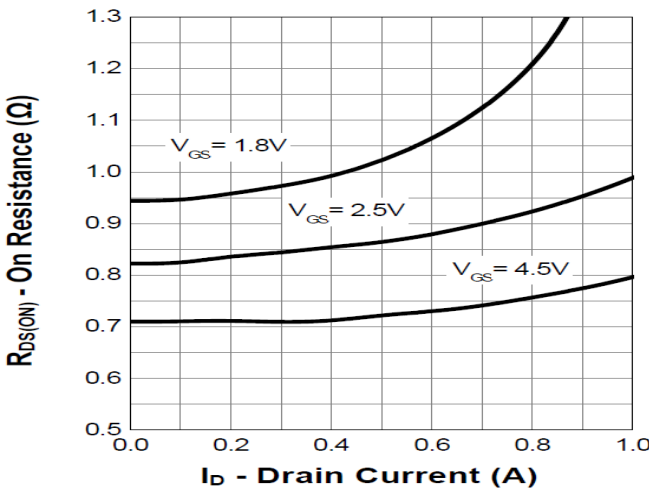


Fig. 4 on-Resistance vs. Gate-Source Voltage

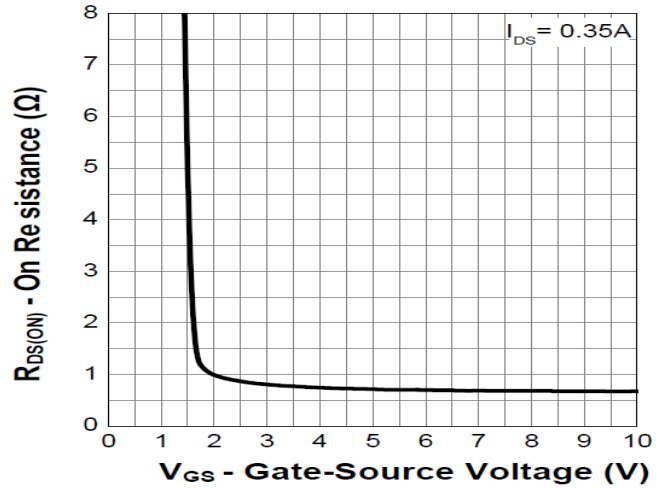


Fig. 5 on-Resistance vs.  $T_j$

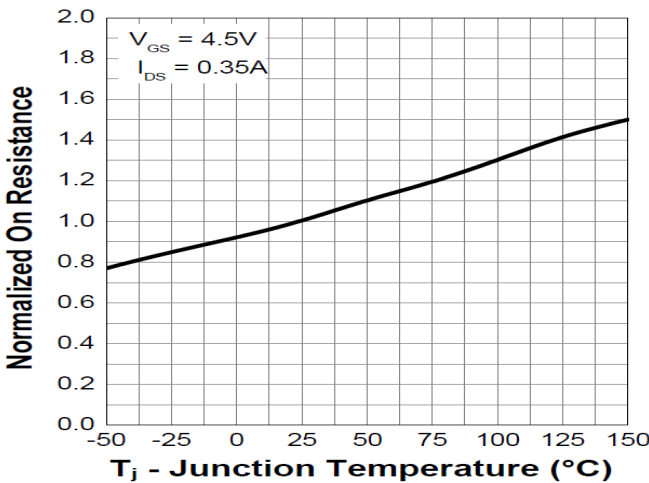
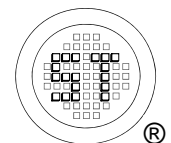
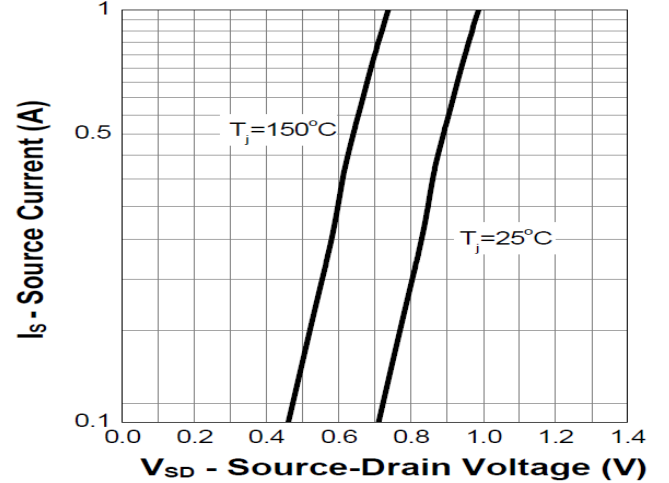


Fig. 6 Typical Forward Characteristics



## Electrical characteristics curves

Fig. 7 Typical Junction Capacitance

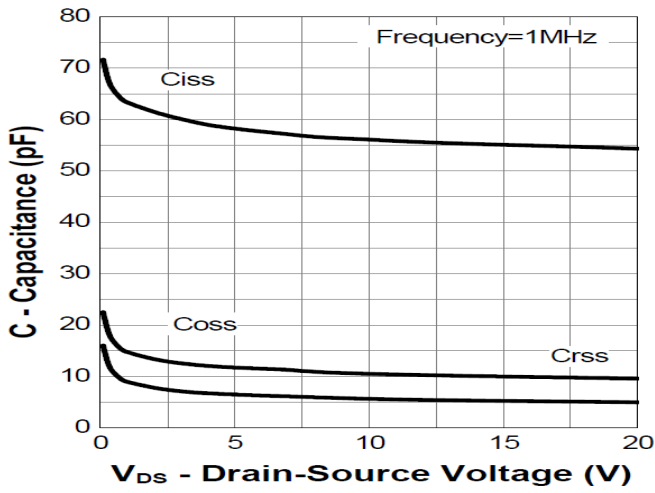
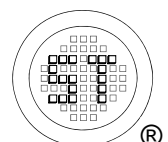
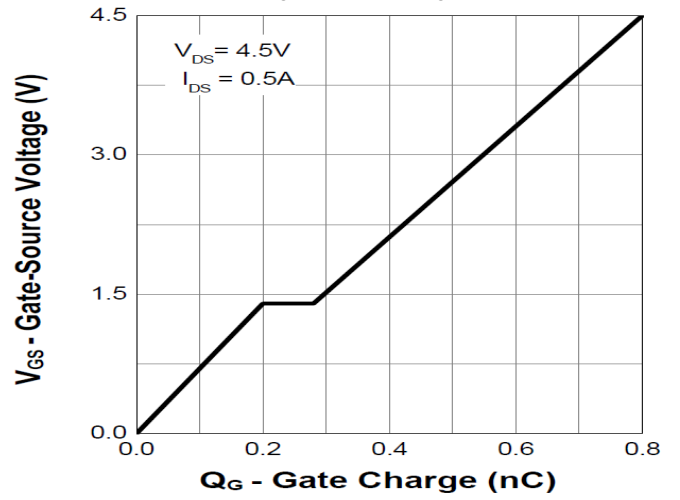


Fig. 8 Gate Charge



## Test Circuits

Fig.1-1 Switching times test circuit

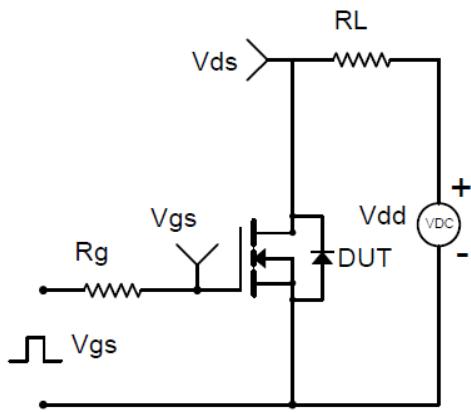


Fig.1-2 Switching Waveform

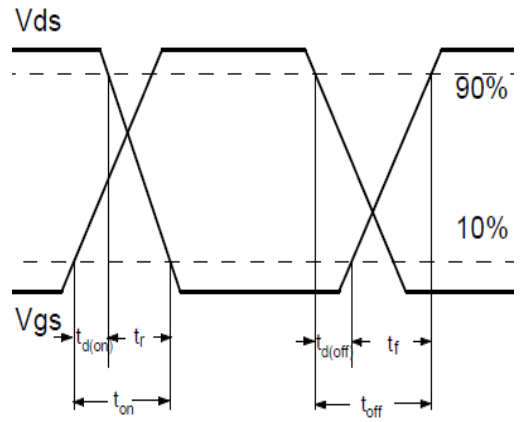


Fig.2-1 Gate charge test circuit

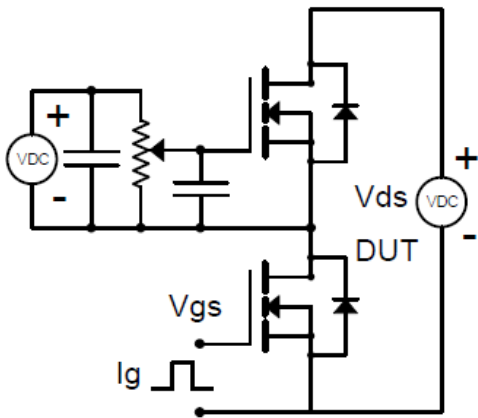
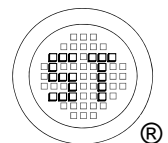
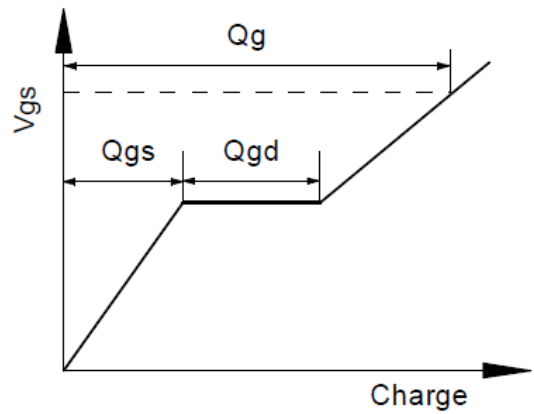


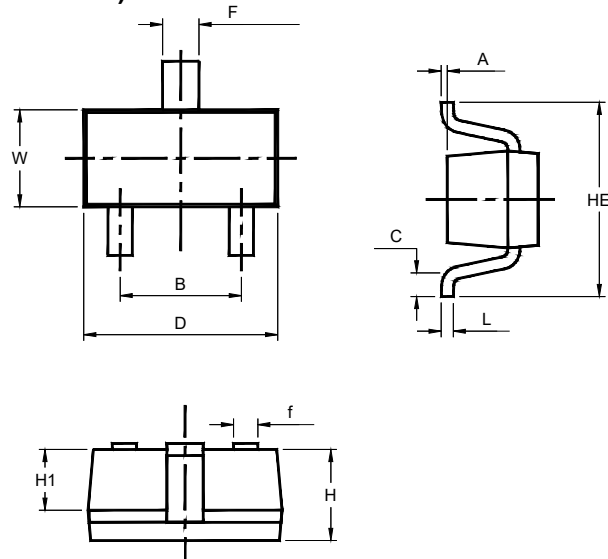
Fig.2-2 Gate charge waveform



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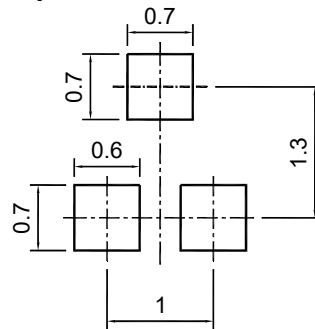
## Package Outline (Dimensions in mm)

SOT-523



UNIT	A	B	C	D	H	H1	HE	F	f	L	W
mm	0.1 MAX.	1.05 0.95	0.17 MIN.	1.7 1.5	0.85 0.65	0.6 0.4	1.7 1.5	0.35 0.25	0.25 0.15	0.15 0.05	0.9 0.7

## Recommended Soldering Footprint

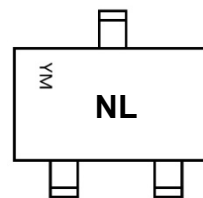


## Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOT-523	8	4 ± 0.1	0.157 ± 0.004	178	7	4,000

## Marking information

- " NL " = Part No.
  - " YM " = Date Code Marking
  - " Y " = Year
  - " M " = Month
- Font type: Arial



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